

Title (en)

METAL ADHESIVE MOULDING METHOD AND THE PRODUCT MADE BY THE METHOD

Title (de)

METALLHAFTFORMVERFAHREN UND DURCH DAS VERFAHREN HERGESTELLTES PRODUKT

Title (fr)

PROCÉDÉ DE MOULAGE PAR ADHÉRENCE DE MÉTAL ET PRODUIT OBTENU AU MOYEN DE CE PROCÉDÉ

Publication

**EP 2142350 A4 20130102 (EN)**

Application

**EP 07807931 A 20070605**

Priority

- KR 2007002715 W 20070605
- KR 20070044976 A 20070509

Abstract (en)

[origin: WO2008140143A1] Provided are a metal adhesive molding method and a product made by the method, in which a metal having an adhesive coated thereon is inserted into an injection mold and synthetic resin is directly injected onto the surface of the adhesive-coated metal. The adhesive is composed of 70-80wt% polyamide, 10-20wt% petroleum resin, 2-7wt% mineral oil, and 3-7wt% amino silane. The method has the advantage of enabling a resin injection-molding product to be reliably combined with a metal having a predetermined shape. Therefore, it is possible to obtain a reliable metal adhesive molding product.

IPC 8 full level

**B29C 45/14** (2006.01); **C09J 177/00** (2006.01)

CPC (source: EP KR US)

**B29C 45/14** (2013.01 - KR); **B29C 45/14311** (2013.01 - EP US); **B29C 45/16** (2013.01 - KR); **C08L 57/00** (2013.01 - EP); **C09J 177/00** (2013.01 - EP); **B29K 2055/02** (2013.01 - EP); **B29K 2069/00** (2013.01 - EP); **B29K 2705/00** (2013.01 - EP); **C08K 5/01** (2013.01 - EP)

Citation (search report)

- [A] EP 1505135 A1 20050209 - EICHENAUER HEIZELEMENTE GMBH [DE]
- [A] WO 2005109984 A2 20051124 - BANG & OLUFSEN AS [DK], et al
- [A] WO 2005061203 A2 20050707 - BOSCH GMBH ROBERT [DE], et al
- [A] WO 2005032793 A1 20050414 - REHAU AG & CO [DE], et al
- [A] DATABASE WPI Week 199431, Derwent World Patents Index; AN 1994-252200, XP002687562
- See references of WO 2008140143A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**WO 2008140143 A1 20081120**; CN 101547778 A 20090930; EP 2142350 A1 20100113; EP 2142350 A4 20130102; JP 2010522654 A 20100708; KR 100792524 B1 20080109

DOCDB simple family (application)

**KR 2007002715 W 20070605**; CN 200780044572 A 20070605; EP 07807931 A 20070605; JP 2010500807 A 20070605; KR 20070044976 A 20070509